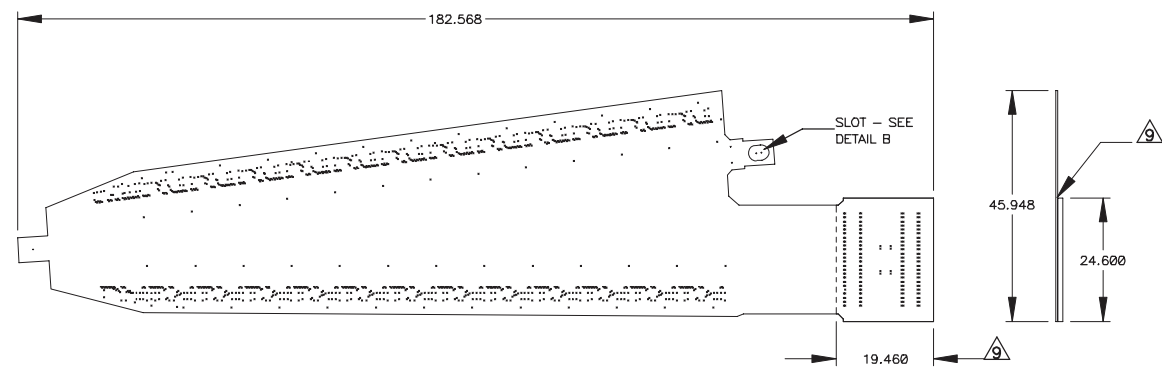


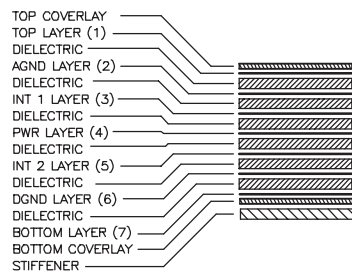
- NOTES:
1. BASE MATERIAL SHALL BE POLYIMIDE 51 UM THK.
 2. TRACE LAYERS TO BE 1/3 OZ. COPPER.
 3. PHOTOIMAGEABLE COVERCOAT 38 UM THK BOTH SIDES.
 4. FABRICATE BOARDS IN ACCORDANCE WITH IPC 6013, CLASS 2.
 5. FABRICATION PROCESS SHALL BE UL APPROVED AND PCB SHALL BE IDENTIFIED WITH MANUFACTURERS APPROVED LOGO AND TYPE DESIGNATION IN ETCH.
 6. CONSTRUCTION OF BOARD AS SHOWN IN DETAIL *A*.
 7. FOR ARTWORK SEE DWG NO. 0064T0403 REV 2C.
 8. ALL EXPOSED PLATED-THROUGH HOLES, PADS AND CONDUCTORS SHALL BE SOLDER COATED OR FUSED TIN-LEAD PLATED 8 UM MIN THICKNESS.
 9. STIFFENER - 1 MM FR-4.
 10. 70 UM TRACES ON LAYER 1 ARE 50 OHMS NOMINAL REFERENCED TO LAYER 2. SEE LAYER STACKUP DETAIL A.
 11. 70 UM TRACES ON LAYER 7 ARE 50 OHMS NOMINAL REFERENCED TO LAYER 6. SEE LAYER STACKUP DETAIL A.
 12. 50 UM TRACES ON LAYER 3 ARE 100 OHMS NOMINAL (DIFFERENTIAL PAIR) REFERENCED TO LAYER 4. SEE LAYER STACKUP DETAIL A.
 13. 50 UM TRACES ON LAYER 5 ARE 100 OHMS NOMINAL (DIFFERENTIAL PAIR) REFERENCED TO LAYER 4. SEE LAYER STACKUP DETAIL A.

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



DETAIL A

SEVEN LAYER CONSTRUCTION
SCALE: NONE

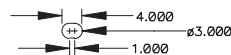


Hole Dia (mm)	Symbol	Quantity	Plated
0.010	+	2	No
0.075	X	1377	Yes
0.965	Y	2	Yes
3.000	+	1	No

SLOT - SEE DETAIL B

DETAIL B

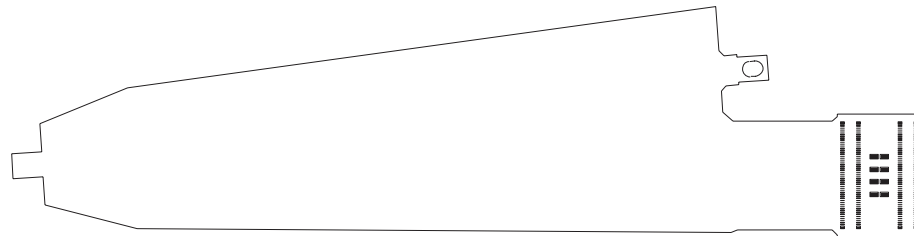
ACTUAL SLOT ROTATED +3.75 DEG



PRELIMINARY, NOT FOR PRODUCTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES ARE IN MILLIMETERS AND APPLY TO THE FINISHED PART TOLERANCE ON: 2 PLACE DEC 3 PLACE DEC ANGLES ± 0.05 ± 0.01 $\pm 1/2^\circ$	THIRD ANGLE PROJECTION 		UNIVERSITY OF NEW MEXICO DEPARTMENT OF PHYSICS AND ASTRONOMY ELECTRONICS SHOP ALBUQUERQUE, NEW MEXICO, USA 87131	
	DRAWN J. BEHRENDT	DATE DATE	TITLE HIGH DENSITY INTERCONNECT FABRICATION	
	APPROVED DATE	APPROVED DATE	SIZE B	DWG NO 0064T0402
MATL 1 2 3 9	FINISH 8	APPROVED DATE	SCALE 1/1	REV 2C
DWG FILENAME 0064T04-2C.pcb		PLOTTED Fri Mar 13, 2009		SHEET 1 OF 1

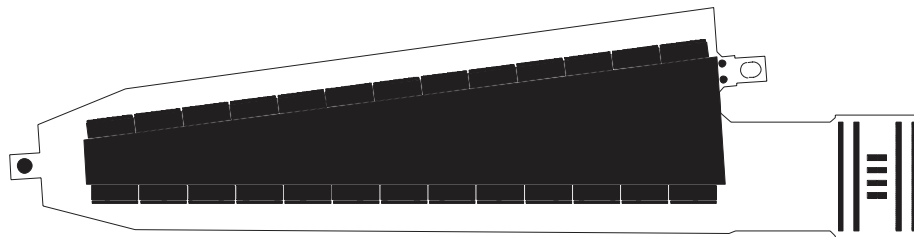
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



TOP PASTE

PRELIMINARY, NOT FOR PRODUCTION

DWG FILENAME 0064T04-2C.pcb PLOTTED Fri Mar 13, 2009	UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES ARE IN MILLIMETERS AND APPLY TO THE FINISHED PART	THIRD ANGLE PROJECTION 		UNIVERSITY OF NEW MEXICO DEPARTMENT OF PHYSICS AND ASTRONOMY ELECTRONICS SHOP ALBUQUERQUE, NEW MEXICO, USA 87131			
		TOLERANCE ON: 2 PLACE DEC 3 PLACE DEC ANGLES ±0.05 ±0.01 ±1/2°	DRAWN J. BEHRENDT	DATE DATE	TITLE HIGH DENSITY INTERCONNECT ARTWORK		
MATL	APPROVED	DATE	APPROVED	DATE	SIZE B	DWG NO 0064T0403	REV 2C
FINISH	APPROVED	DATE	APPROVED	DATE	SCALE 1/1	SHEET 1 OF 11	



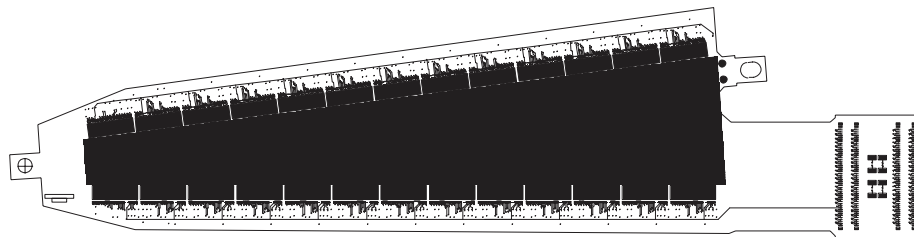
TOP COVER

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 2	



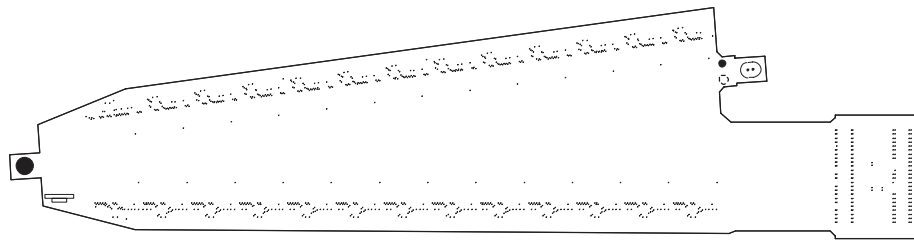
TOP

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 3	



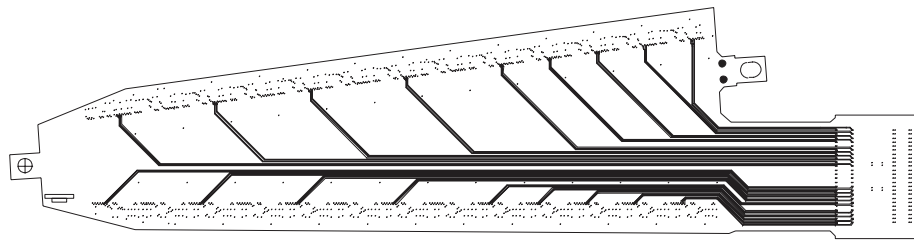
AGND

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 4	



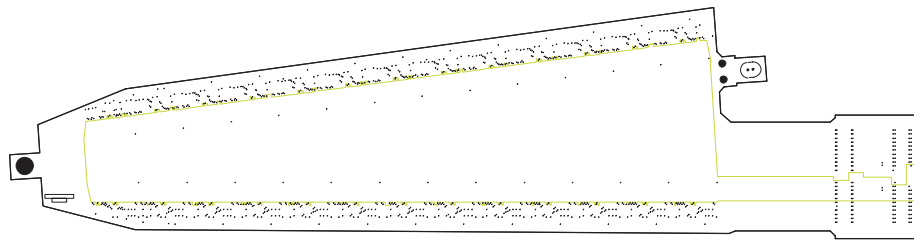
INT1

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 5	



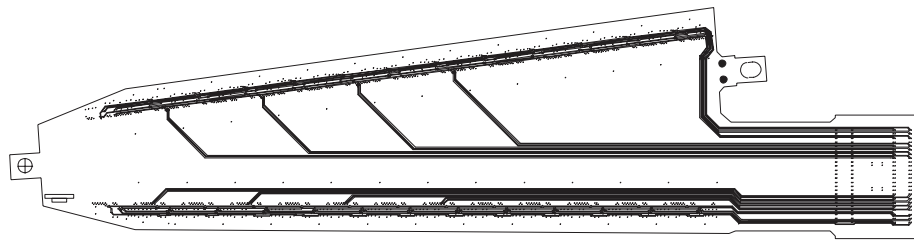
PWR

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 6	



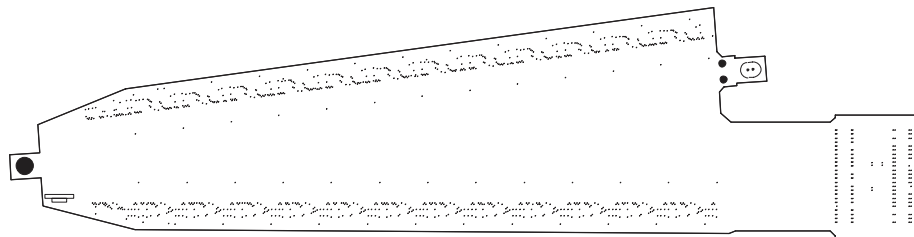
INT2

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 7	



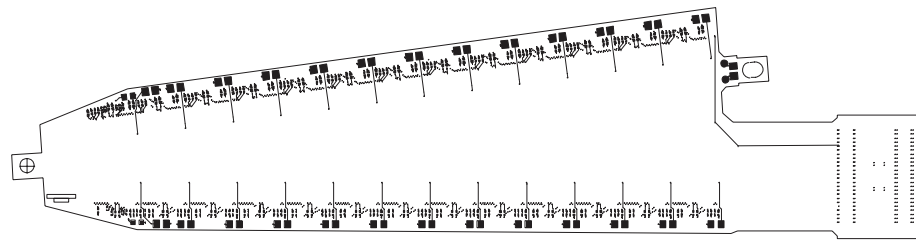
DGND

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 8	



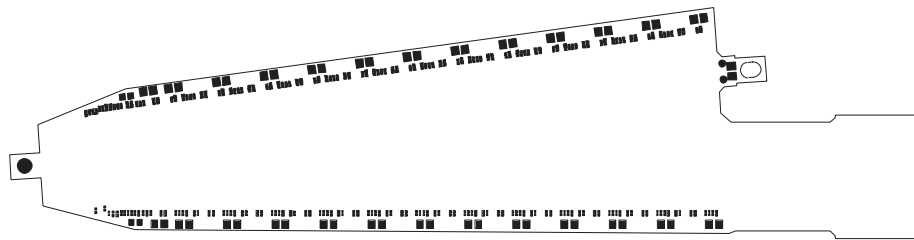
BOTTOM

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 9	



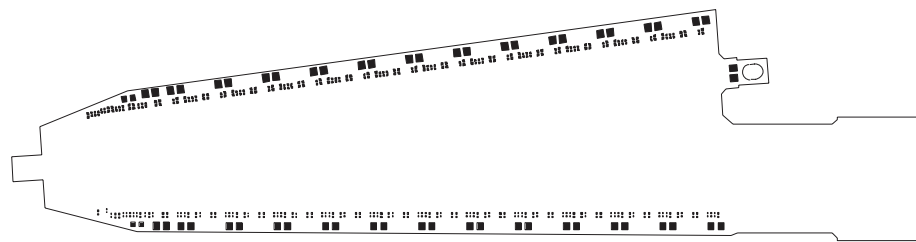
BOT COVER

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 10	



BOT PASTE

PRELIMINARY, NOT FOR PRODUCTION

ARTWORK

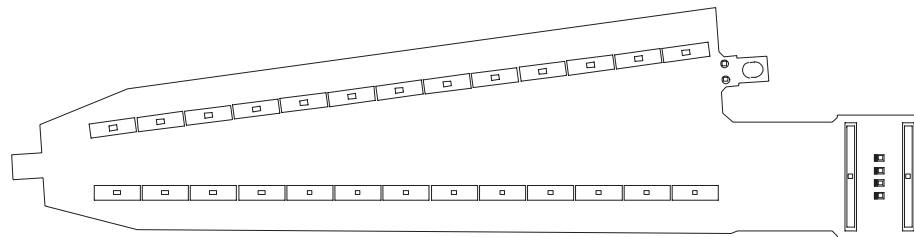
PLOTTED
Fri Mar 13, 2009

SIZE B	_____	DWG NO 0064T0403	REV 2C
SCALE 1/1	_____	SHEET 11	

NOTES:

1. REFERENCE ELECTRICAL SCHEMATIC DRAWING, 0064T0401 REV -1.
2. ASSEMBLE AND SOLDER PER IPC-A-610A AND IPC J-STD-001D .
3. OBSERVE POLARITY OF CAPACITORS, ETC..
4. ELECTRICAL REFERENCE DESIGNATIONS ARE FOR REFERENCE ONLY AND NEED NOT APPEAR ON THE PARTS OR COMPONENTS UNLESS OTHERWISE SPECIFIED.
5. FOR PICK & PLACE LOCATIONS USE FILE 0064T04-2C.PNP.
6. FOR TEST POINT LOCATIONS USE FILE 0064T04-2C.TST.

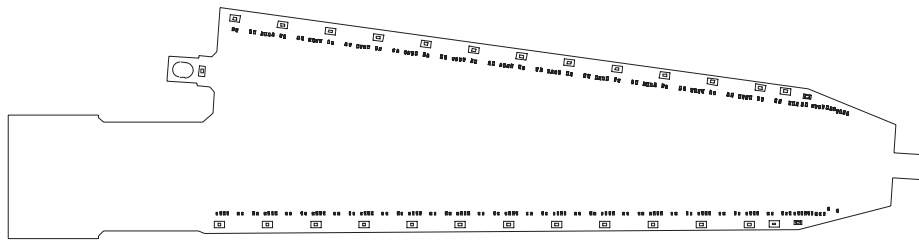
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



TOP ASSY

PRELIMINARY, NOT FOR PRODUCTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES ARE IN MILLIMETERS AND APPLY TO THE FINISHED PART		THIRD ANGLE PROJECTION 		UNIVERSITY OF NEW MEXICO DEPARTMENT OF PHYSICS AND ASTRONOMY ELECTRONICS SHOP ALBUQUERQUE, NEW MEXICO, USA 87131	
DRAWN J. BEHRENDT		DATE		TITLE HIGH DENSITY INTERCONNECT ASSEMBLY	
APPROVED		DATE		SIZE B	
APPROVED		DATE		DWG NO 0064T0404	
APPROVED		DATE		REV 2C	
TOLERANCE ON: 2 PLACE DEC 3 PLACE DEC ANGLES ±0.05 ±0.01 ±1/2°		MATERIAL		SCALE 1/1	
FINISH				SHEET 1 OF 2	
DWG FILENAME 0064T04-2C.pcb					
PLOTTED Fri Mar 13, 2009					



BOT ASSY
VIEWED FROM BOTTOM OF BOARD

PRELIMINARY, NOT FOR PRODUCTION

ASSEMBLY

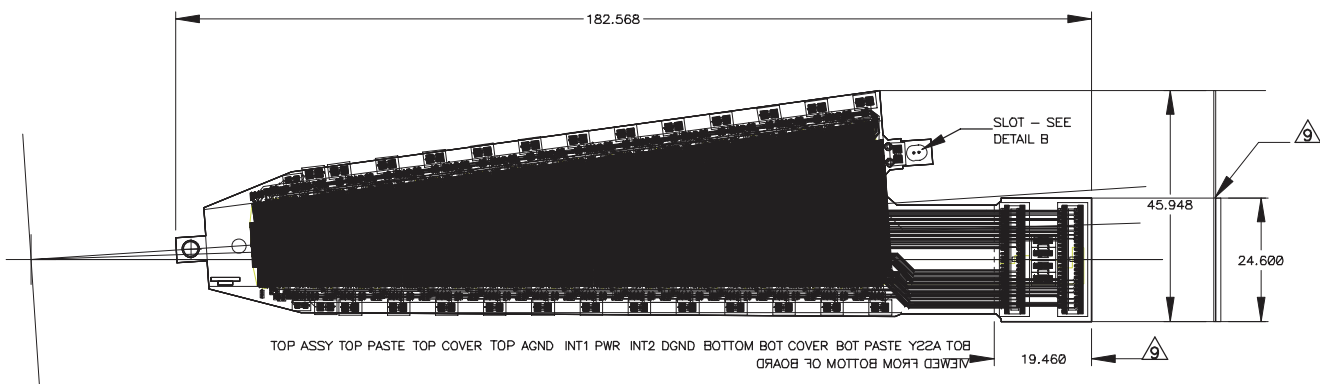
REV	0004104	DWG NO.		SIZE	B
SC				SCALE	1:1
SHEET					

PLotted
Fit Mar 12, 2008

NOTES:

1. REFER TO ELECTRICAL DRAWING 0064T0401 REV -1.
2. ASSEMBLE AND SOLDER PER IPC-A-610A AND IPC J-STD-001D.
3. TRACE LAYERS TO BE 1/310Z COPPER.
4. OBSERVE POLARITY OF CAPACITORS, ETC..
5. ELECTRONIC COMPONENTS SHALL BE ON BOTH SIDES.
6. REFERENCE ONLY AND NEED NOT APPEAR ON THE PARTS FABRIKATE BOARDS IN ACCORDANCE WITH IPC 6013, CLASS 2, OR COMPONENTS UNLESS OTHERWISE SPECIFIED.
7. FABRIKATE ON PLACES ON WHICH SELF PROTECTING COP.
8. SOLUBLE IDENTIFICATION SURFACE RES APPROVED. LOGO AND TYPE DESIGNATION IN ETCH.
9. CONSTRUCTION OF BOARD AS SHOWN IN DETAIL "A".
10. FOR ARTWORK SEE DWG NO. 0064T0403 REV 2C.
11. ALL EXPOSED PLATED-THROUGH HOLES, PADS AND CONDUCTORS SHALL BE SOLDER COATED OR FUSED TIN-LEAD PLATED 8 UM MIN THICKNESS.
12. STIFFENER - 1 MM FR-4.
13. 70 UM TRACES ON LAYER 1 ARE 50 OHMS NOMINAL REFERENCED TO LAYER 2. SEE LAYER STACKUP DETAIL A.
14. 70 UM TRACES ON LAYER 7 ARE 50 OHMS NOMINAL REFERENCED TO LAYER 6. SEE LAYER STACKUP DETAIL A.
15. 50 UM TRACES ON LAYER 3 ARE 100 OHMS NOMINAL (DIFFERENTIAL PAIR) REFERENCED TO LAYER 4. SEE LAYER STACKUP DETAIL A.
16. 50 UM TRACES ON LAYER 5 ARE 100 OHMS NOMINAL (DIFFERENTIAL PAIR) REFERENCED TO LAYER 4. SEE LAYER STACKUP DETAIL A.

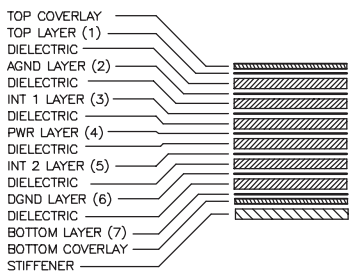
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



TOP ASSY TOP PASTE TOP COVER TOP AGND INT1 PWR INT2 DGND BOTTOM BOT COVER BOT PASTE Y22A TOB
NEWED FROM BOTTOM BOARD

DETAIL A

SEVEN LAYER CONSTRUCTION
SCALE: NONE

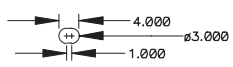


Drill Table			
Hole Dia (mm)	Symbol	Quantity	Plated
0.010	+	2	No
0.075	X	1377	Yes
0.965	Y	2	Yes
3.000	+	1	No

SLOT - SEE DETAIL B

DETAIL B

ACTUAL SLOT ROTATED +3.75 DEG



PRELIMINARY, NOT FOR PRODUCTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES ARE IN MILLIMETERS AND APPLY TO THE FINISHED PART TOLERANCE ON: 2 PLACE DEC 3 PLACE DEC ANGLES ±0.05 ±0.01 ±1/2°	THIRD ANGLE PROJECTION 	UNIVERSITY OF NEW MEXICO DEPARTMENT OF PHYSICS AND ASTRONOMY ELECTRONICS SHOP ALBUQUERQUE, NEW MEXICO, USA 87131	
	DRAWN J. BEHRENDT		DATE DATE
	APPROVED DATE		APPROVED DATE
TITLE HIGH DENSITY INTERCONNECT FABRICATION	SIZE B	DWG NO 0064T0403	
MATL FINISH	APPROVED DATE	REV 2C	
DWG FILENAME 0064T04-2C.pcb PLOTTED Fri Mar 13, 2009	PLOT JOB 0000	SCALE 1/1 SHEET 1 OF 21	

ASSEMBLY

VBR	0040T0400	OM DWG	SIZE
CS	0004T040		B
SHEET	3		